

APPARATUS FOR CONNECTING A SEMICONDUCTOR DIE TO A  
SUBSTRATE AND METHOD THEREFOR

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Abstract of the Disclosure

10 A pad area of a substrate (50) includes a conductive trace (52) formed on the  
substrate (50) having a first surface area, the first surface area being of a first  
solderability. A conductive pad (56) is formed on the first surface area of the  
conductive trace (52). The conductive pad (56) has a second surface area, the  
15 second surface area being of a second solderability. The second solderability is  
greater than the first solderability. Because of the different solderabilities, a solder  
bump (46) on the semiconductor die (40) can be reflowed and connected to the  
second surface area without using a soldermask (28) to contain the melted solder  
on the second surface area.

09746976.122100